QUALIFICATION REPORT SUMMARY

RELIABILITY LABORATORY

PCN #: CENO-01UVKE616

Date:
April 22, 2026

Qualification of MMT as an additional assembly site for selected 24FC512, 24LC512, 24AA512, 24LC256, 24AA256, 24FC256, 24FC64, 24LC128, 24AA128 and 24FC128 device families available in 8L DFN-S (6x5x0.9mm) package. This is a Q006 Grade 1 qualification.

Package Qualification Report

Purpose: Qualification of MMT as an additional assembly site for selected 24FC512, 24LC512, 24AA512, 24LC256, 24AA256, 24FC256, 24FC64, 24LC128, 24AA128 and 24FC128 device families available in 8L DFN-S (6x5x0.9mm) package. This is a Q006 Grade 1 qualification.

CCB No. 7907

Misc.	Assembly site	MMT
	BD Number	BD-003900-01
	MP Code (MPC)	669024A6XS00
	Part Number (CPN)	25CSM01-E/MF
	Assembly Shipping Media (T/R, Tube/Tray)	T&R
	Base Quantity Multiple (BQM)	3300
Lead-Frame	Paddle size	173 x 173 mils
	Material	A194
	DAP Surface Prep	Bare Cu
	Treatment	Roughened
	Process	Etched
	Lead-lock	Locking hole
	Part Number	10100879
	Lead Plating	Matte tin
Bond Wire	Material	CuPdAu
Die Attach	Part Number	QMI519
	Conductive	Yes
MC	Part Number	G700LTD
PKG	PKG Type	DFN-S
	Pin/Ball Count	8
	PKG width/size	6x5x0.9 mm

Package Qualification Report

Manufacturing Information:

Assembly Lot No.
MMT-263301084.000
MMT-263301129.000
MMT-263301130.000

Conclusion:

Qualification of 66902 mask / 25CSM01-E/MF product / 0.8 mil CuPdAu wire in 8L DFN-S 6x5x0.9 mm package at MMT site is qualified for MSL1 at 260ºC as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards

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Package Qualification Report

Moisture Soak Precondition Prior to Stresses

Test Method	JESD22-A113, JEDEC J-STD-020		
Test Condition	**MSL1**: 150ºC 24 hours Bake, 168 hours Moisture Soak at 85ºC/85%RH, 3x Reflow at 260ºC		
Required Sample Size	231 units each lot / 3 lots;		
Lot ID	**R2501550-1 MMT-263301084.000**	**R2501550-2 MMT-263301129.000**	**R2501550-3 MMT-263301130.000**
Electrical Results (Fail / Pass)	0/231	0/231	0/231
Electrical Test Tester: NEXTEST_PT	25°C, 85°C, and 125°C		
Result:	**Passed**		

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Package Qualification Report

High Temp Storage

Test Method	JESD22-A103		
Test Condition	175°C / 500 hours		
Required Sample Size	45 units each lot / 3 lots;		
Lot ID	**R2501550-1** **MMT-263301084.000**	**R2501550-2** **MMT-263301129.000**	**R2501550-3** **MMT-263301130.000**
Electrical Results (Fail / Pass)	0/45	0/45	0/45
Electrical Test Tester: NEXTEST_PT	25°C, 85°C, and 125°C		
Result:	**Passed**		

High Temp Storage

Test Method	JESD22-A103		
Test Condition	175°C / 1000 hours		
Required Sample Size	45 units each lot / 3 lots;		
Lot ID	**R2501550-1** **MMT-263301084.000**	**R2501550-2** **MMT-263301129.000**	**R2501550-3** **MMT-263301130.000**
Electrical Results (Fail / Pass)	0/45	0/45	0/45
Electrical Test Tester: NEXTEST_PT	25°C, 85°C, and 125°C		
Result:	**Passed**		

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Package Qualification Report

Temperature Cycling

Test Method	JESD22-A104		
Test Condition	-55ºC / +150ºC Air to Air / 1000 Cycles		
Required Sample Size	77 units each lot / 3 lots; WBP/WBS		
Lot ID	**R2501550-1** **MMT-263301084.000**	**R2501550-2** **MMT-263301129.000**	**R2501550-3** **MMT-263301130.000**
Electrical Results (Fail / Pass)	0/77	0/77	0/77
WBP (Fail / Pass)	0/3	0/3	0/3
WBS (Fail / Pass)	0/3	0/3	0/3
Electrical Test Tester: NEXTEST_PT	25°C, 85°C, and 125°C		
Result:	**Passed**		

Temperature Cycling

Test Method	JESD22-A104		
Test Condition	-55ºC / +150ºC Air to Air / 2000 Cycles		
Required Sample Size	77 units each lot / 3 lots; WBP/WBS		
Lot ID	**R2501550-1** **MMT-263301084.000**	**R2501550-2** **MMT-263301129.000**	**R2501550-3** **MMT-263301130.000**
Electrical Results (Fail / Pass)	0/77	0/77	0/77
WBP (Fail / Pass)	0/3	0/3	0/3
WBS (Fail / Pass)	0/3	0/3	0/3
Electrical Test Tester: NEXTEST_PT	25°C, 85°C, and 125°C		
Result:	**Passed**		

Package Qualification Report

Biased HAST

Test Method	JESD22-A110		
Test Condition	+130ºC / 85%RH / 96 hours / Bias Voltage: 5.6V		
Required Sample Size	77 units each lot / 3 lots; WBP/WBS		
Lot ID	**R2501550-1** **MMT-263301084.000**	**R2501550-2** **MMT-263301129.000**	**R2501550-3** **MMT-263301130.000**
Electrical Results (Fail / Pass)	0/77	0/77	0/77
WBP (Fail / Pass)	0/3	0/3	0/3
WBS (Fail / Pass)	0/3	0/3	0/3
Electrical Test Tester: NEXTEST_PT	25°C, 85°C, and 125°C		
Result:	**Passed**		

Biased HAST

Test Method	JESD22-A110		
Test Condition	+130ºC / 85%RH / 192 hours / Bias Voltage: 5.6V		
Required Sample Size	77 units each lot / 3 lots; WBP/WBS		
Lot ID	**R2501550-1** **MMT-263301084.000**	**R2501550-2** **MMT-263301129.000**	**R2501550-3** **MMT-263301130.000**
Electrical Results (Fail / Pass)	0/77	0/77	0/77
WBP (Fail / Pass)	0/3	0/3	0/3
WBS (Fail / Pass)	0/3	0/3	0/3
Electrical Test Tester: NEXTEST_PT	25°C, 85°C, and 125°C		
Result:	**Passed**		

MICROCHIP

Package Qualification Report

Unbiased HAST

Test Method	JESD22-A118		
Test Condition	+130ºC / 85%RH / 96 hours		
Required Sample Size	77 units each lot / 3 lots;		
Lot ID	**R2501550-1** **MMT-263301084.000**	**R2501550-2** **MMT-263301129.000**	**R2501550-3** **MMT-263301130.000**
Electrical Results (Fail / Pass)	0/77	0/77	0/77
Electrical Test Tester: NEXTEST_PT	25°C		
Result:	Passed		

Solderability (0 Hr) Method 1: Dip and Look

Test Method	J-STD-002 / JESD22B-102
Test Condition / Criteria	Pb-free 8 hours Steam age. Dip at 245ºC, 100% leads >95% lead coverage
Required Sample Size	22 units / 1 lot
Visual Result (Fail / Pass)	0/22 - **Passed**

Physical Dimension (0Hr)

Test Method	JESD22 B100 and B108
Test Criteria	Within package diagram dimension
Required Sample Size	10 units each lot / 3 lots
Result (Fail / Pass)	0/30 – **Passed**

Wire Pull

Test Method	Mil. Std. 883-2011
Test Criteria	Bond Strength Data Assembly
Required Sample Size	5 units / 1 lot
Result (Fail / Pass)	0/5 - **Passed**

Bond Shear

Test Method	CDF-AEC-Q100-001
Test Criteria	Bond Strength Data Assembly
Required Sample Size	5 units / 1 lot
Result (Fail / Pass)	0/5 - **Passed**